# Hadron Calorimeter Summary

Andy White SiD Workshop, SLAC October 2006

### Overview

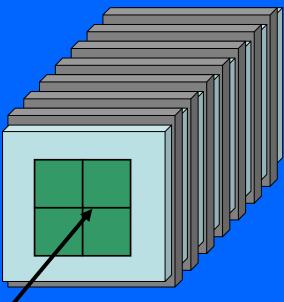
- Digital HCal (GEM, RPC) status, plans.
- Analog/Scintillator HCal/TCMT/SiPM status and plans.
- [Note: Simulation studies to follow in PFA talk]

### Slice test: RPCs and GEMs

Uses the 40 DCAL ASICs from the 2<sup>nd</sup> prototype run

Equip ~8 chambers with 4 DCAL chips each

256 channels/chamber ~2000 channels total



Order additional DCAL ASICs to equip GEM prototypes

Chambers interleaved with 20 mm copper - steel absorber plates

Electronic readout system (almost) identical to the one of the prototype section

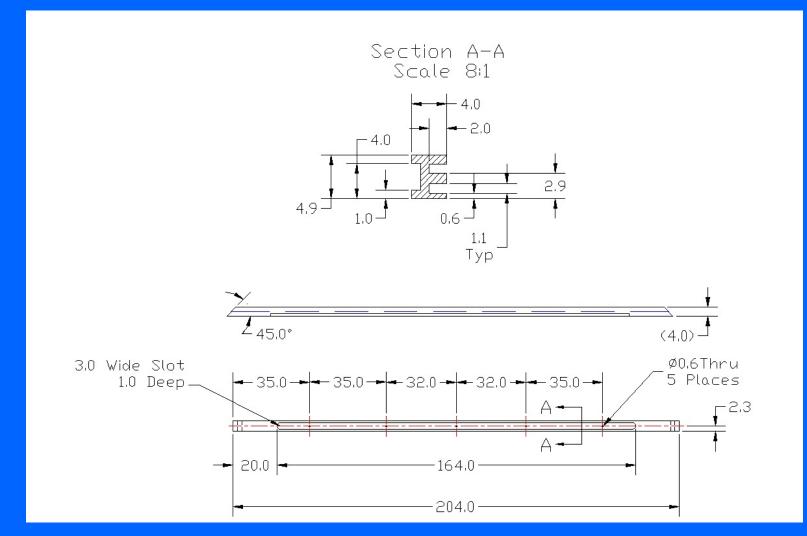
Tests in MTBF beam planned for March 2007

 $\rightarrow$  Measure efficiency, pad multiplicity, rate capability of individual chambers  $\rightarrow$  Measure hadronic showers and compare to simulation

Validate RPC/GEM approach to calorimetry

Validate concept of electronic readout

### **Mechanical: RPC design**

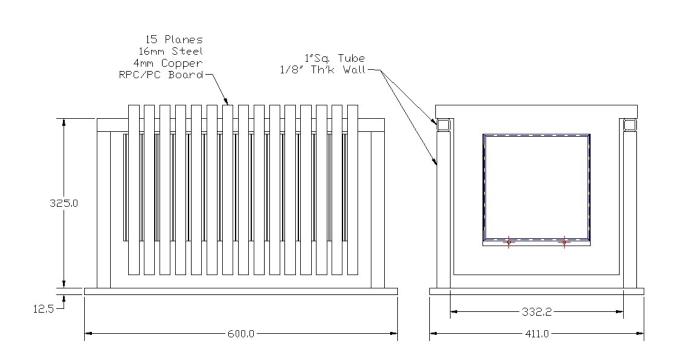


All chambers: channels, resistive paint, glass in hand  $1^{st}$  chamber  $\rightarrow$  being assembled

V Guarino (ANL)

V Guarino (ANL)

### **Mechanical: Stack**



Design accommodates 20 x 20 cm<sup>2</sup> RPCs as well as 30 x 30 cm<sup>2</sup> GEMs All parts in hand, stack will be assembled shortly



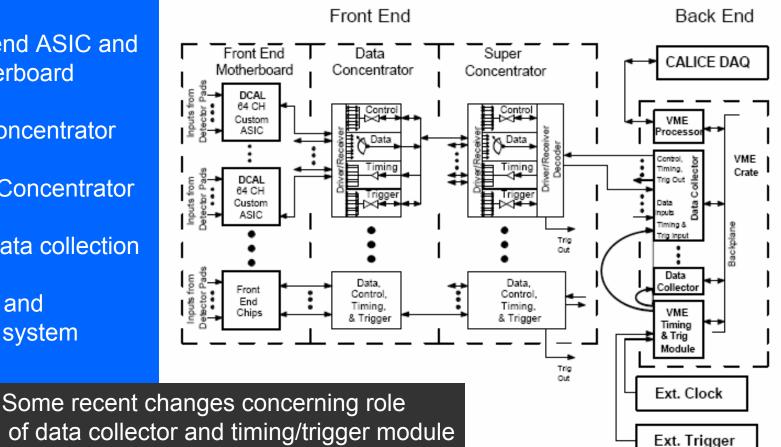
### **Electronic Readout System for Prototype Section**

40 layers à 1 m<sup>2</sup>  $\rightarrow$  400,000 readout channels

More than all of DØ in Run I

Front-end ASIC and motherboard

- Ш Data concentrator
- Super Concentrator
- VME data collection IV
- **Trigger and**  $\bigvee$ timing system



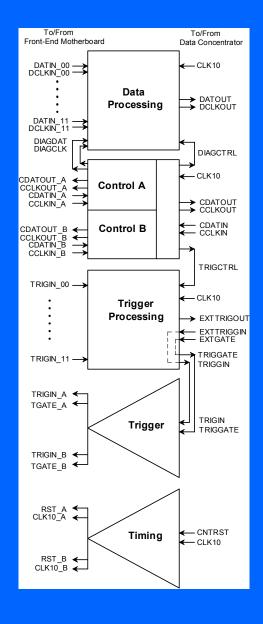
#### G Drake (ANL)

### **Data concentrator boards**

Functionality defined Protocol to data collector defined Being designed

### **Timing and trigger module**

Functionality defined Possibly to be designed by Chicago



#### E Hazen (Boston)

### **Data collector boards**

#### **Three options considered**

• Re-use of CRC boards (CALICE)

Difficult to obtain Not matched to our application (trigger) Not considered anymore

#### Re-use of CMS boards (Boston)

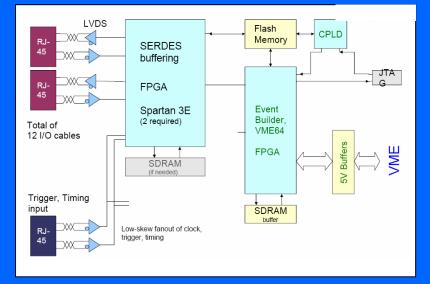
Possible, but many drawbacks (availability) Costly (~ \$70k for prototype section) Main advantage: could be ready in 3 months

#### New design

Not much more expensive (~\$80k for prototype section) (~\$60k for slice test)

Will be exactly what we want Time needed ~ 6 months

Decided to go for new design → contribution of Boston University Interface meeting on September 22<sup>nd</sup> Design work started



## **DCAL chip**

#### 1<sup>st</sup> version

 $\rightarrow$  extensively tested with computer controlled interface

 $\rightarrow$  all functions performed as expected

#### Redesign

- $\rightarrow$  decrease of gain by factor 20 (GEMs) or 100 (RPCs)
- $\rightarrow$  decoupling of clocks (readout and front-end)

#### 2<sup>nd</sup> version

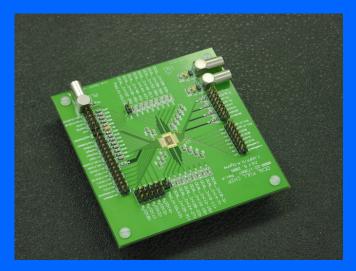
- $\rightarrow$  submitted on July 22<sup>nd</sup>
- $\rightarrow$  40 chips (packaged) in hand

#### **Test board**

- $\rightarrow$  redesign of test board (changes in pin layout etc.) complete
- $\rightarrow$  boards fabricated
- $\rightarrow$  chip mounted on test board

#### Testing (2/40)

- $\rightarrow$  all software written
- $\rightarrow$  unless serious problems: tests complete by mid-November





#### G Drake (ANL)

### Pad and front-end boards

**New concept** 

#### **Pad boards**

two-layer board containing pads can be sized as big as necessary cheap and simple conductive epoxy to fill vias

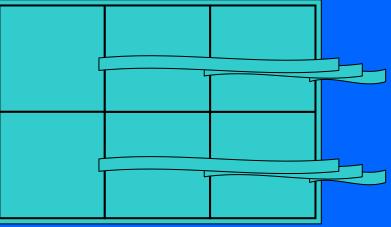
#### **Front-end boards**

multi-layer board 16 x 16 cm<sup>2</sup> contain all transfer lines, houses DCAL chip expensive (blind and buried vias) and tough to design

#### Connections

Prototypes of pad boards expected by next week

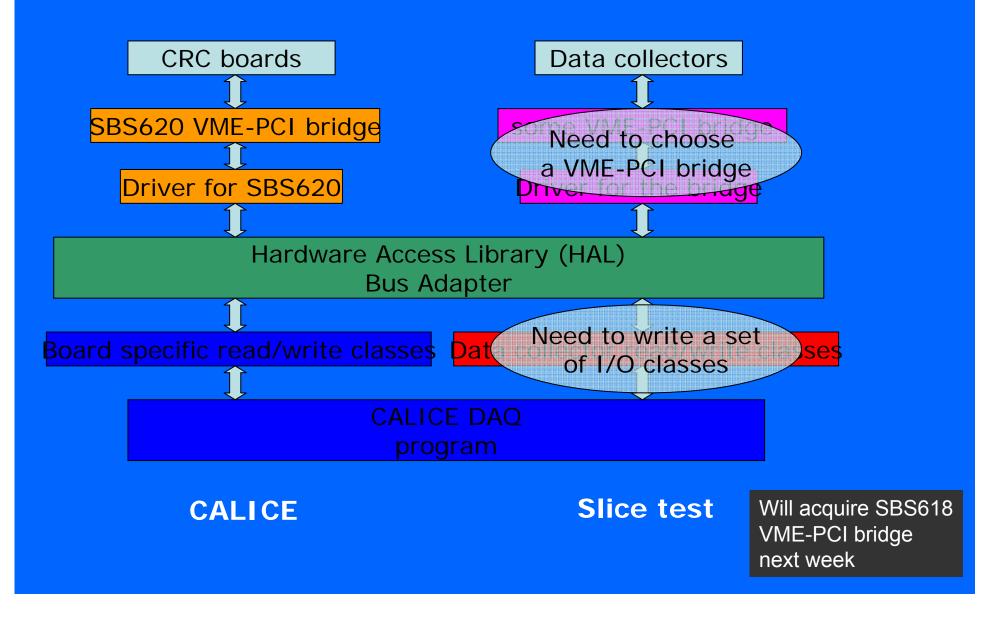
board to board with conductive glue on each pad (being tested) cables for connection to data concentrators



L Xia (ANL)

### **DAQ** software

Particular challenge to be compatible with CALICE software



### Beam telescope, HV, and gas

#### **Beam telescope**

J Li, A White, J Yu (UTA)

6 counters  $(3 \times (1 \times 1 \text{ cm}^2) + 1 \times (4 \times 4 \text{ cm}^2) + 2 \times (19 \times 19 \text{ cm}^2)$ Mounted on rigid structure In production

#### **HV modules**

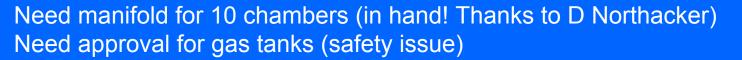
E Norbeck (lowa)

Need separate supplies for each chamber Modules (from FNAL pool) being tested

With additional RC-filter perform similarly to our Bertran unit in analog tests (RABBIT system) Still need to perform tests with digital readout

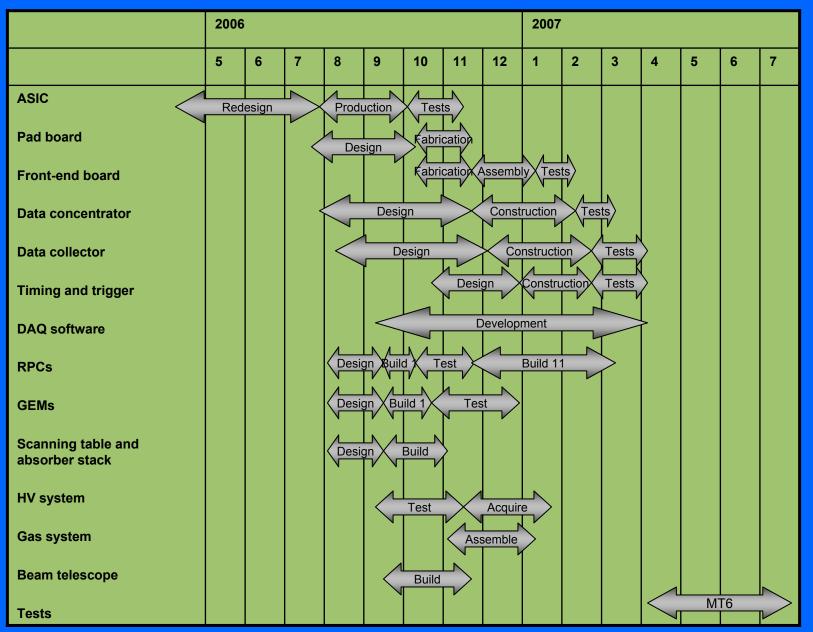
E Norbeck (lowa)

**Gas system** 





### **Time scales**



1 m<sup>3</sup> Prototype Section

### **Costs and Funding**

A) Slice test is funded by LCDRD06, LDRD06 and ANL-HEP, and Fermilab funds

B) Prototype section not yet funded, but...

Stack	Item	Cost	Contingency	Total
RPC stack	M&S	607,200	194,600	801,800
	Labor	243,075	99,625	342,700
	Total	850,275	294,225	1,144,500
GEM stack <sup>*</sup>	M&S	400,000	165,000	565,000
* Reusing most of the RPC electronics	Labor	280,460	40,700	321,160
	Total	680,460	205,700	886,160
Both stacks	M&S	1007,200	359,600	1366,800
	Labor	523,535	140,325	663,860
	Total	1,530,735	499,925	2,030,660

Proposal for supplemental funds for \$500k/year over two years submitted to DOE Help from ANL (LDRD), ANL-HEP, FNAL expected...

### Funding

#### LCRD funds for 2006

RPCs (ANL, Boston, Chicago, Iowa)\$98kGEMs (UTA, Washington)\$60k

#### Supplemental LCRD funds for 2006/7

Available funds

\$1,200k/year?

Submitted pre-proposal for RPC/GEM DHCAL

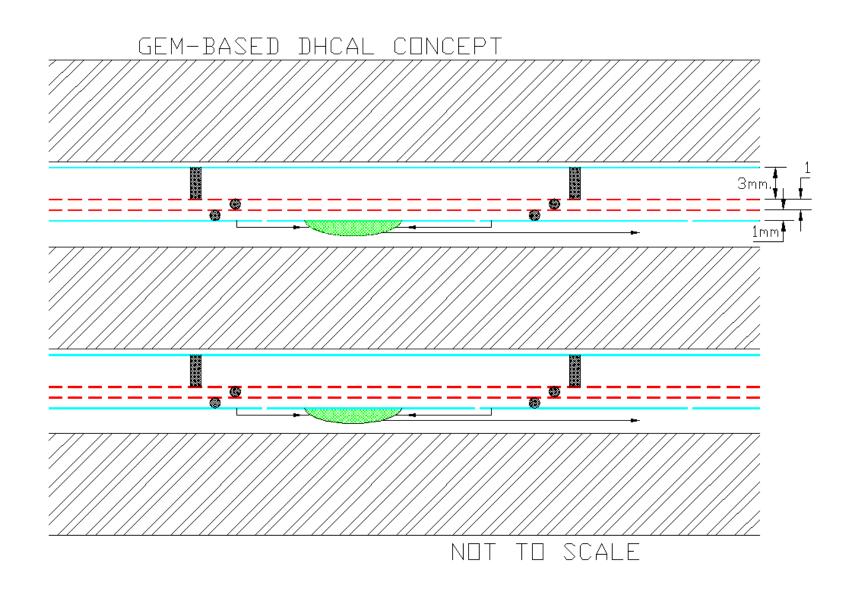
Requested \$1,200k for 2006 ~\$800k for 2007

- 2006 build RPC-DHCAL continue R&D on GEMs
- 2007 test RPC-DHCAL at MTBF build GEM stack

2008 test GEM-stack

DOE asked us to submit proposal for \$500k/year (done)

## **GEM-based** Digital Calorimeter Concept



# GEM Foils from 3M

- 30cm x 30cm foils made with three types of coating:
  - a) bare copper
  - b) "organic polymer" coating
  - c) gold plating

- HV tests made on all three types -> conclusion is that we prefer to use the uncoated foils.

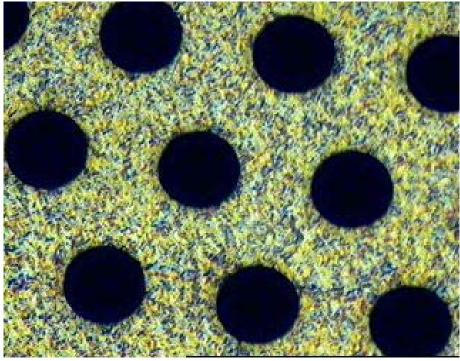
- We are using the uncoated foils in our current 30cm x 30cm chambers.

## 3M 30cm x 30cm GEM foils

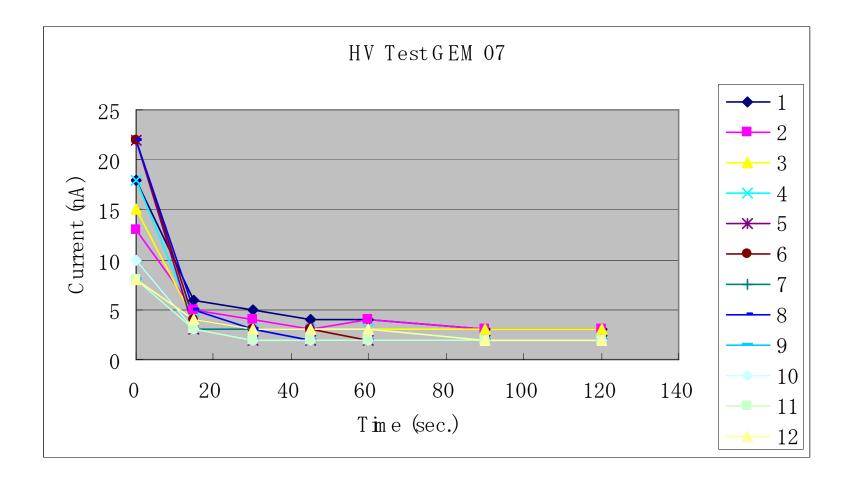
12 HV sectors on one side of each foil.



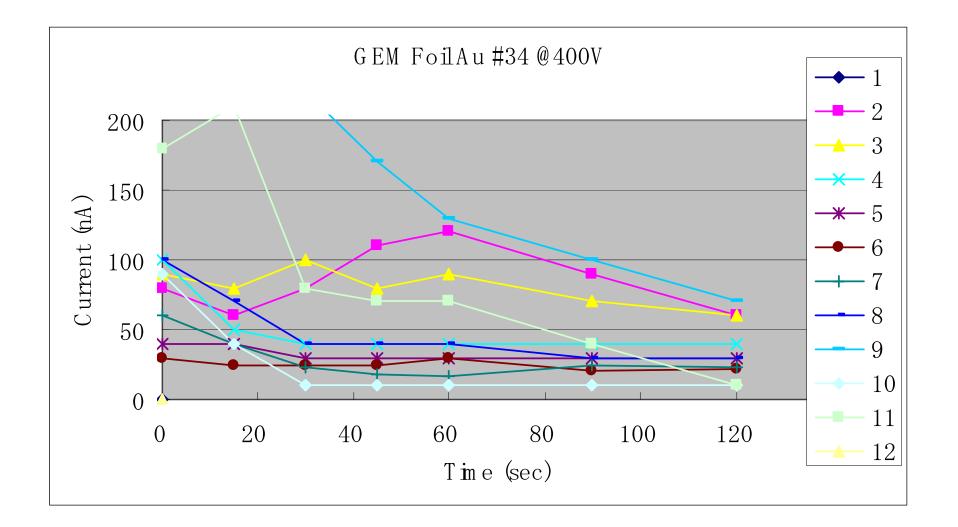
Magnified section of a 3M GEM foil.



## HV tests on uncoated GEM foil



# GEM Au #34



## 3M Long (90cm) GEM Foil Design

-3M has setup a formal internal project to develop larger foils for the 1m<sup>3</sup> prototype stack (the 30x30cm<sup>2</sup> foil development did not require 3M process modification).

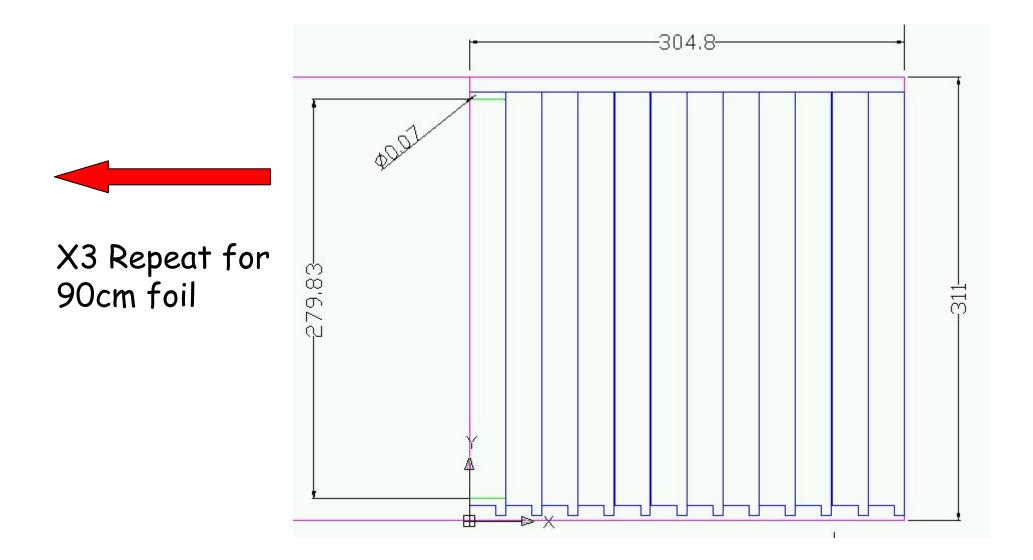
- Reusing the artwork (masks) from the 30cm x 30cm foil development.

- Small area needed for re-registration foil moves through etching station.

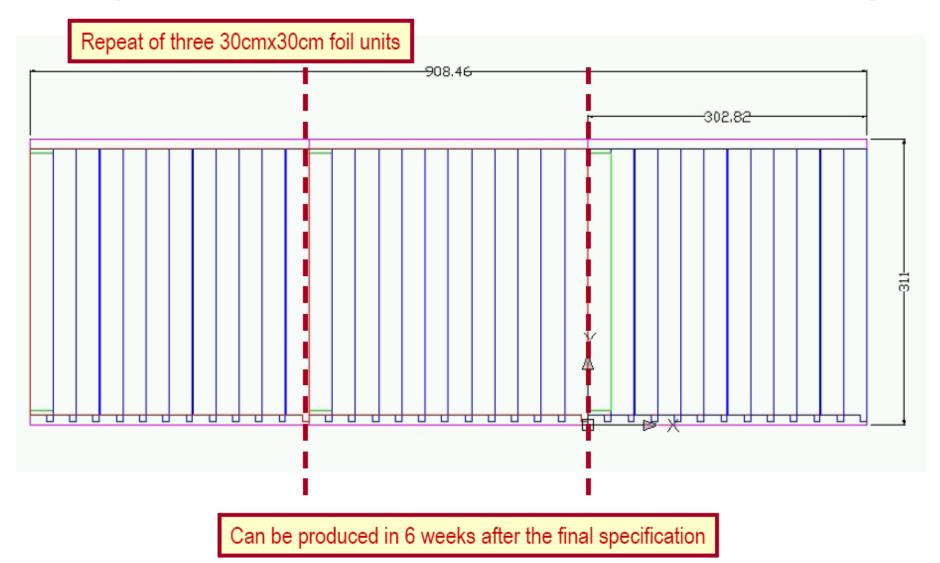
- Anticipate first samples in November '06.

- First long chamber construction will follow 30cm x 30cm chamber construction for Slice Test.

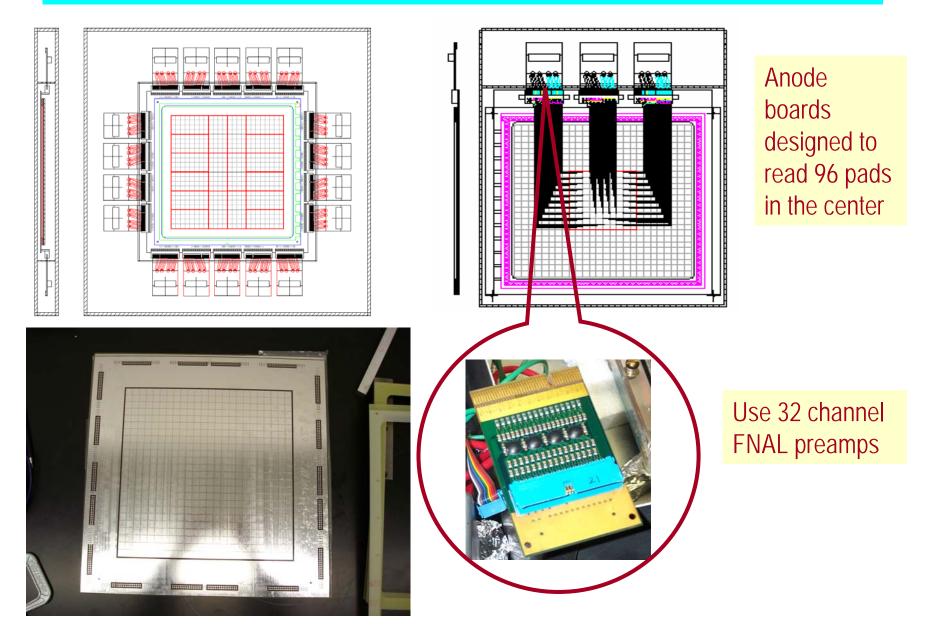
## 3M Long (90cm) GEM Foil Design



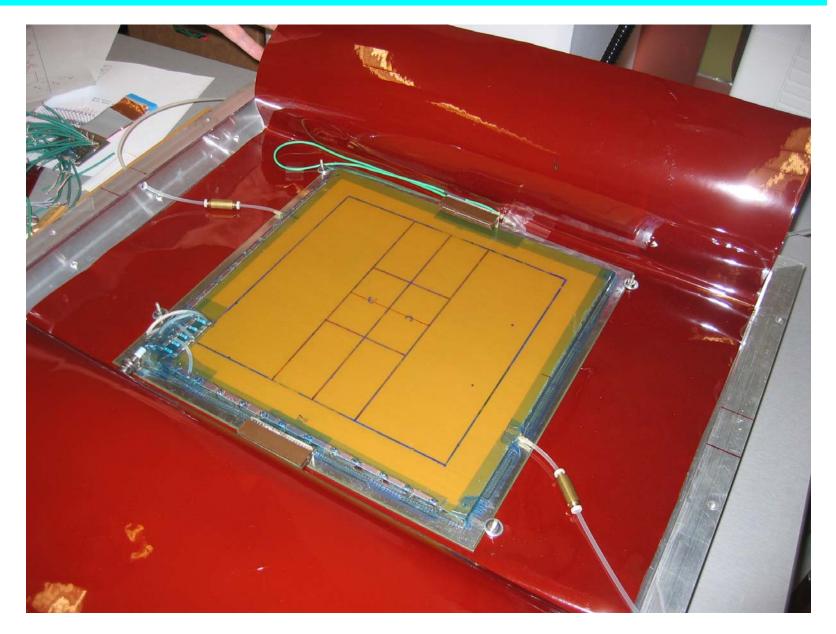
# Proposed Initial 3M 30cmx100cm Foil Design



## 30cm x 30cm GEM chamber(s)



## 30cm x 30cm GEM chamber



## UTA GEM-DHCAL exposure

- 4-pad GEM area (2 x 2 pads) exposed to full beam

- Beam scans ~800mm x 50mm area every 2 sec, with 30ps pulse of  $10^{10}$  e<sup>-</sup>/pulse over a 5 cm<sup>2</sup> area, or ~ $10^9$  e<sup>-</sup>/sec on an anode pad.

- Total exposure ~2000sec

-> Estimate ~2  $\times$  10<sup>12</sup> e<sup>-</sup>/pad (~ 1.6  $\times$  10<sup>-2</sup> mC/mm<sup>2</sup>) and GEM chamber continued normal operation.

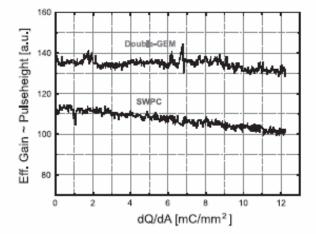


Fig. 3. Previous aging measurement of a double-GEM detector with Ar–CO<sub>2</sub> (70:30): effective gain versus accumulated charge dQ/dA.

- Much above total hits/10y/pad at ILC
- Much below any damage region for decrease in gain.

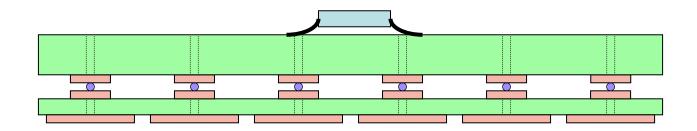
DCAL chip ANL/FNAL

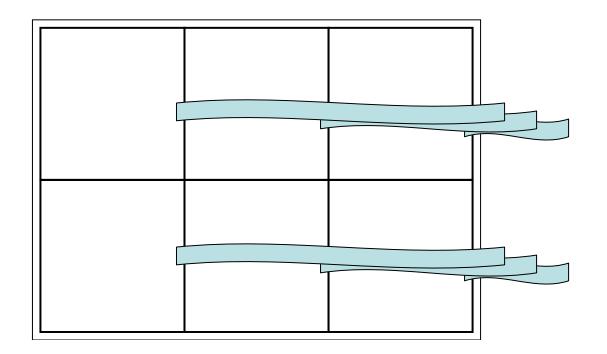
Digital hit output

RPC and GEM capabilities

GEM signals:

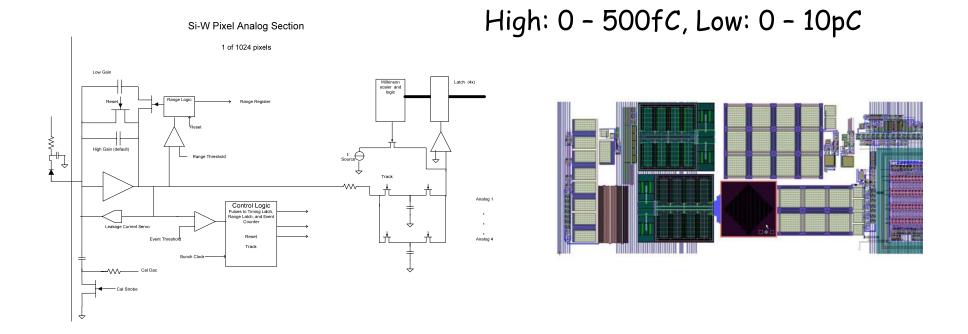
minimum signal ~10fC, maximum signal ~few pC





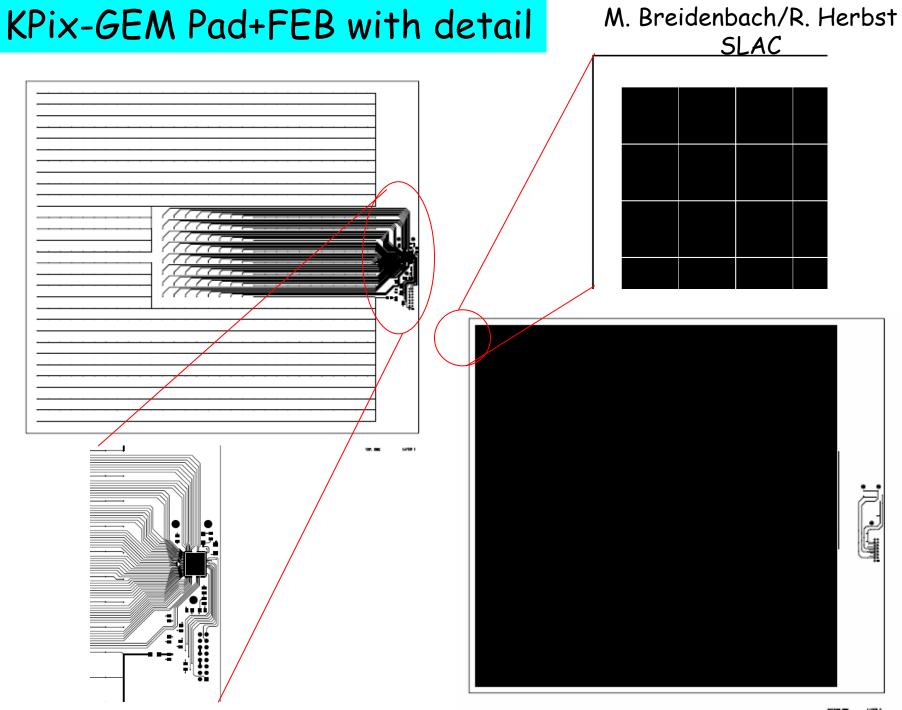
## KPix Readout chip/SLAC

Analog output. Two gain ranges



v3 - 64 channels - September 2006 (with GEM changes)

v4 - 64/128/1024 channels(??) end of 2006/early 2007?



DOTTOM DEC. LATER

## Schedule/budget for GEM-DHCAL

May 2006 - 30x30cm<sup>2</sup> chamber built, initial tests.

- low energy e- beam tests in Korea.

Summer 2006 - built additional 30x30cm<sup>2</sup> chambers.

- work with ANL/SLAC on anode board designs.

Fall 2006 - Tests of GEM chambers with KPix, DCal chips as chips and boards become available.

- Build 2-3 chamber each for DCAL and KPix for Slice Test.
- build larger GEM chambers (~1m x 30cm) when 3M foils are available.

Early 2007 - Slice Test RPC and GEM chambers with DCAL and v3 KPix.

## Scintillator/SiPM TCMT/HCal

Scintillator tiles read out via SiPM's is one of the technologies studied for the SiD HCal.

NIU has been working on this in the context of the CALICE Collaboration and applying the same technology to the proposed TCMT = Tail Catcher/Muon Tracker.

NOTE! All the CALICE HCAL/TCMT results here are preliminary!

# The CALICE TCMT prototype

All 16 layers fully instrumented (8 fine + 8 coarse)

Alternate x,y orientations

Fine section (~ 2cm absorber) Coarse section (~ 10cm absorber)

20 channels (strips) / cassette Each strip is 100 x 5 x 0.5 cm<sup>3</sup>,

### beam



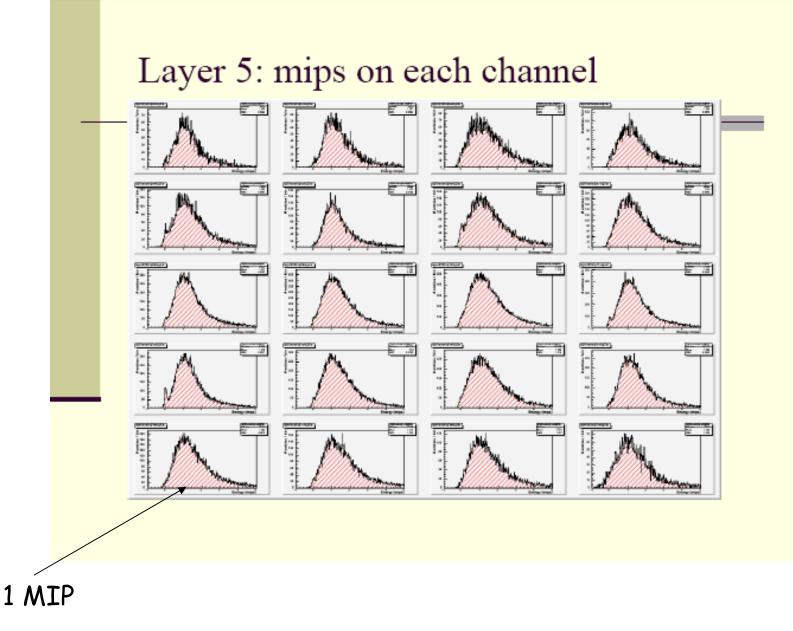
HCAL

TCMT



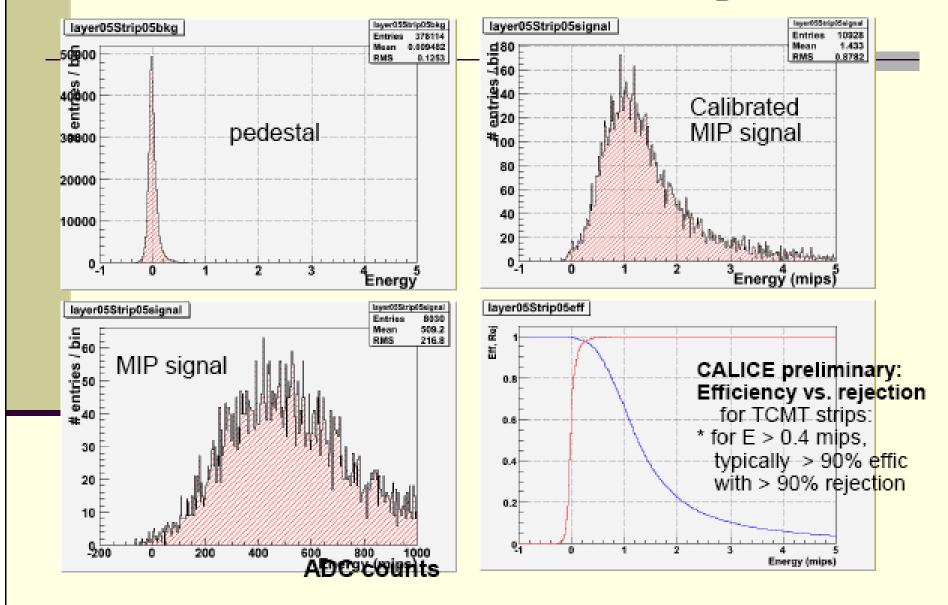
Scintillator/SiPM HCal and TCMT



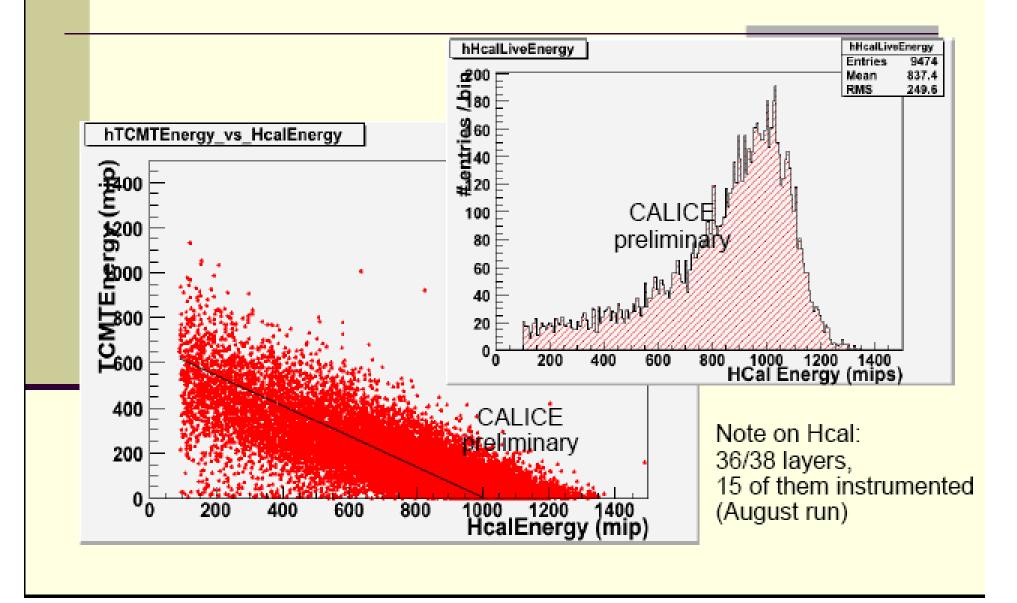


Calibrated hit energies in terms of E(MIP)

### A closer look into a TCMT strip



### 80 GeV pions: Heal x TCMT correlation



### 80 GeV Pions – adding TCMT energy

#### Combining the TCMT hits: a factor of 1.4445 was applied to the TCMT hits

800 1000 1200 1400 HCal Energy (mips)

Much better, but Ecal hits not included yet... Work in Progress !

HCal only

CALICE

600

helpersurillesturitest

400

hHcalLiveEnergy

<u>අ</u>00 අ00

360 Ē40 <u>.</u> 20

100

80

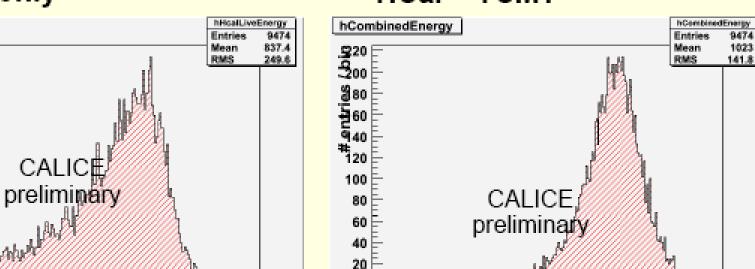
60

40

20

0<sub>0</sub>

200



200

400

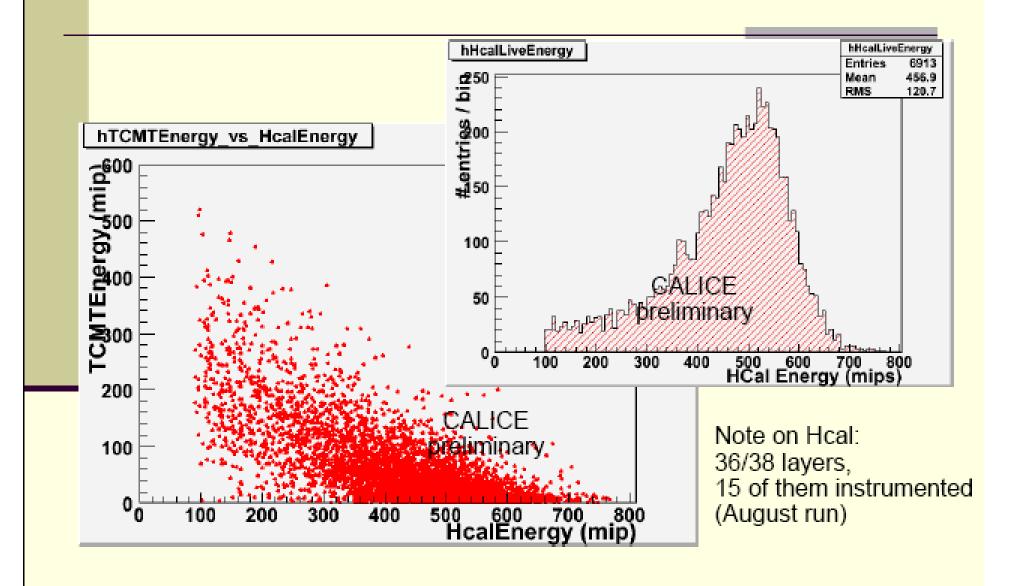
600

00

#### HCal + TCMT

800 1000 1200 1400 HCal+TCMT Energy (a.u.)

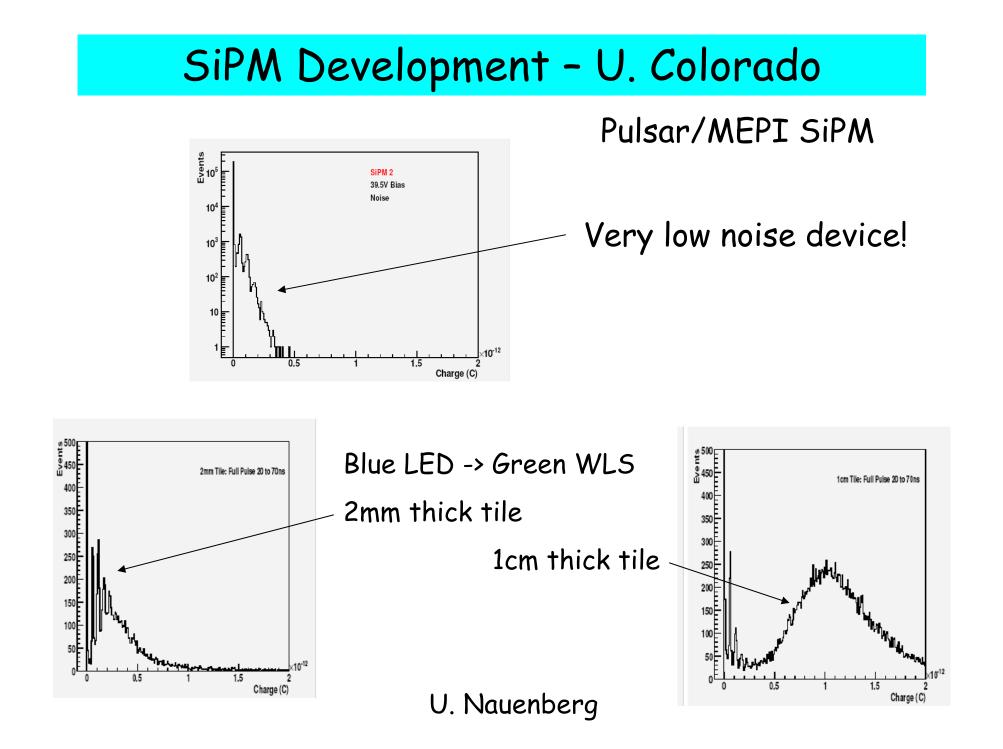
### 30 GeV pions: Heal x TCMT correlation



## Scintillator/SiPM TCMT/HCal

- Present plans call for completion of the CALICE HCal and ECal in early 2007 and subsequent running at CERN

- Target for move of ECal/HCal/TCMT to Fermilab is September 2007 - more of this in Test Beam talk...



## Scintillator/SiPM TCMT/HCal

From the R&D so far:

- Extruded Scintillator/SiPM's are living up to expectations and are a viable technology .

- focussing on detailed performance studies (e.g. uniformity).

- starting to consider cost/performance for HCAL.

### Hadron Calorimeter - Conclusions

- High level of R&D activity for AHCAL/DHCAL/TCMT.
- RPC and GEM plan Slice Test at Fermilab in early 2007.
- Initial results on Scintillator AHCAL/TCMT from CERN.
- Latest versions of readout chips for RPC/GEM look close to acceptance.

- Plans for DHCAL stacks (RPC, GEM) to be tested at Fermilab 2007-8.

- Finally: planning for longer term R&D - developing a plan for a section of a calorimeter that could be part of a final SiD detector. This is a multi-year, expensive, exercise - in parallel with TDR...